

Method and device for bonding substrates

Abstract

A method is proposed for bonding a first substrate (1,6) with a second substrate (2), with the following sequence:

- production of a first amorphous layer (1a,6a) on the first substrate (1,6) and/or production of a second amorphous layer (2a) on the second substrate (2),
- bonding of the first substrate (1,6) with the second substrate (2) at the amorphous layer (1a,2a,6a) or at the amorphous layers (1a,2a,6a) to form a substrate stack (3),
- irradiation of the amorphous layer (1a,2a,6a) or the amorphous layers (1a,2a,6a) with radiation (5) in such a way that the amorphous layer (1a,2a,6a) or the amorphous layers (1a,2a,6a) is/are transformed into a crystalline layer or crystalline layers.

See in this regard fig. 1a